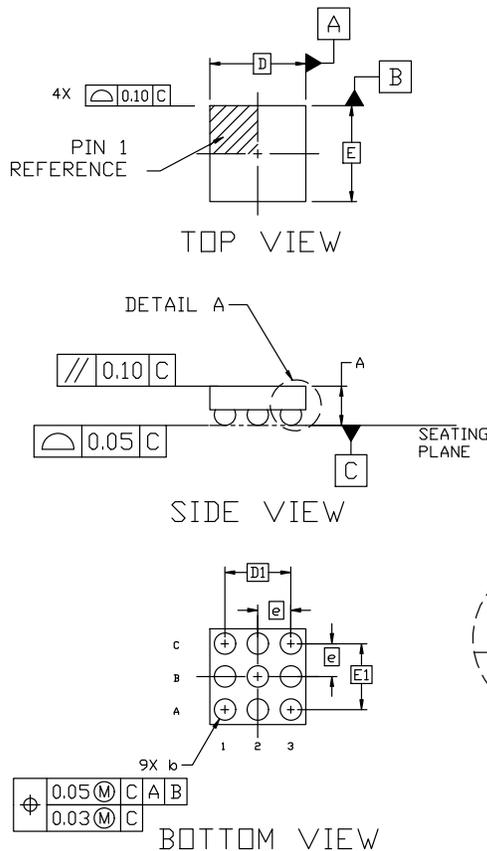


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## 9 PIN FLIP-CHIP 1.45x1.45x0.596 CASE 499AL ISSUE A

DATE 21 JUN 2022

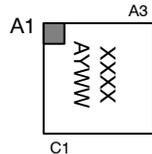


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION  $b$  IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

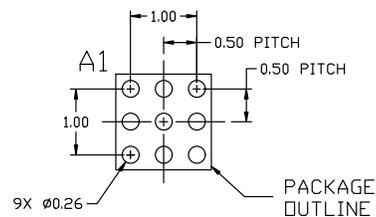
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.541	0.596	0.651
A1	0.206	0.236	0.266
A2	0.335	0.360	0.385
$b$	0.289	0.319	0.349
D	1.450 BSC		
D1	1.000 BSC		
E	1.450 BSC		
E1	1.000 BSC		
$e$	0.50 BSC		

### GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G or  $\blacksquare$  = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " $\blacksquare$ ", may or may not be present. Some products may not follow the Generic Marking.



### RECOMMENDED MOUNTING FOOTPRINT\*

- \* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>9 PIN FLIP-CHIP 1.45x1.45x0.596</b>	<b>PAGE 1 OF 1</b>

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